L Number	Hits	Search Text	DB	Time stamp
-	2	"10314713"	EPO; JPO; DERWENT	2004/09/08 15:31
-	2	"10314716"	EPO; JPO; DERWENT	2004/09/08 10:02
-	2	"08325436"	EPO; JPO; DERWENT	2004/09/08 10:03
-	2	"08325437"	EPO; JPO; DERWENT	2004/09/08 10:04
-	2	"08325438"	EPO; JPO; DERWENT	2004/09/08 10:05
-	2	"09316445"	EPO; JPO; DERWENT	2004/09/08 10:05
-	3	"10126052"	EPO; JPO; DERWENT	2004/09/08 10:06
-	2	"11209754"	EPO; JPO; DERWENT	2004/09/08 10:07
-	1	20020120019.pn.	US-PGPUB	2004/09/13 09:19
-	0	20020120019.URPN.	USPAT	2004/09/08 11:30
-	1	("6780894").PN.	USPAT; US-PGPUB	2004/09/13 11:52
-	1265	"epoxy resin cured"	USPAT; US-PGPUB	2004/09/08 15:52
-	707512	decomp$ dissol$	USPAT; US-PGPUB	2004/09/08 15:31
-	32	"epoxy resin cured" with (decomp$ dissol$)	USPAT; US-PGPUB	2004/09/08 15:37
-	872	510/175,176.ccls.	USPAT; US-PGPUB	2004/09/13 12:55
-	473	588/205,207.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:56
-	0	510/175,176.ccls. and 588/205,207.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/10 08:53
-	1830	"epoxy resin cured"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:38
-	0	510/175,176.ccls. and "epoxy resin cured"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:38
-	179755	"epoxy resin"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:58
-	31	510/175,176.ccls. and "epoxy resin"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:38

(handwritten: 1449 art)

-	111058	("epoxy resin").ab,ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:38
-	1	(510/175,176.ccls. and "epoxy resin") and (("epoxy resin").ab,ti.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:39
-	30	(510/175,176.ccls. and "epoxy resin") not ((510/175,176.ccls. and "epoxy resin") and (("epoxy resin").ab,ti.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/08 15:39

		49	("6433102" "6455625" "6465531" "6423467" "4374076" "6338869" "6391948" "4576896" "4571314" "5624471" "4803022" "5578343" "4861672" "4873128" "5644003" "5646204" "5839510" "6209643" "6209643" "4439489" "4482399" "4495020" "4895767" "5344854" "5356689" "5527841" "5725960" "5728439" "5851847" "5861680" "5902643" "5968471" "5993909" "6124023" "6165816" "6255367" "6261738" "6265782" "6270616" "6309757" "6335060" "6344306" "6344505" "6361872" "6365671" "6423471" "6432544" "6440568" "6458864" "6458908").pn.	*PLUS patents*	USPAT; US-PGPUB	2004/09/10 08:44
-		1	3551204.pn.	*Bolger et al.*	USPAT; US-PGPUB	2004/09/10 08:44
-		16	3551204.URPN.		USPAT	2004/09/10 08:44
-		5	("2710843" "2662837" "2479628" "2445064" "2367273").pn.	*art cited in*	USPAT	2004/09/13 09:20
-		1	6780894.pn.		USPAT; US-PGPUB	2004/09/13 11:52
-		401	521/40,40.5.ccls.		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:55

-		872	510/175,176.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:55
-		473	588/205,207.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:56
-		3047	134/38,42.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:56
-		1603	252/364.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 13:15
-		0	521/40,40.5.ccls. and 510/175,176.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:56
-		0	521/40,40.5.ccls. and 588/205,207.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:56
-		4	521/40,40.5.ccls. and 134/38,42.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:57
-		0	521/40,40.5.ccls. and 252/364.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:57
-		179953	"epoxy resin"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:58
-		21	521/40,40.5.ccls. and "epoxy resin"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 12:58
-		3047	134/38,42.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 13:14
-		1603	252/364.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 13:15
-		290	134/38,42.ccls. and 252/364.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 13:15